

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT5338558

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
A REUM JUN	01/15/2019
HYE WON RYOO	01/15/2019
HO IN JUN	01/15/2019
SEOK KEUN AHN	01/15/2019
JI HYE YU	01/15/2019
GI SEOK JEONG	01/15/2019
RECEIVING PARTY DATA	
Name:	SAMSUNG ELECTRO-MECHANICS CO., LTD.
Street Address:	MAEYOUNG-RO 150 (MAETAN-DONG), YOUNGTONG-GU
City:	SUWON-SI, GYEONGGI-DO
State/Country:	KOREA, REPUBLIC OF
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16255077
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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ATTORNEY DOCKET NUMBER:	123193-7644
NAME OF SUBMITTER:	HOSANG LEE
SIGNATURE:	/Hosang Lee/
DATE SIGNED:	01/23/2019
Total Attachments: 3	
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other relevant treaties;

I hereby authorize and request the United States Patent and Trademark Office and officials in patent offices in foreign countries to issue any and all of said Letters Patent to the ASSIGNEE as the assignee of my entire right, title, and interest in and to the same, for the sole use and benefit of the ASSIGNEE, and its lawful successors and assigns, to the full end of the term for which said Letters Patent may be granted;

I hereby grant the attorney of record the power to insert on this Assignment any further identification that may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office or other authority for recordation of this document;

I hereby covenant that I have the full right to convey the interest assigned by this Assignment, and I have not executed and will not execute any agreement in conflict with this Assignment; and

Further, I hereby further covenant and agree that I will, without further consideration, communicate with the ASSIGNEE, and its lawful successors and assigns, any facts known to me respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said ASSIGNEE, and its lawful successors or assigns, execute all divisional, continuation, continuation-in-part, and reissue applications, make all rightful oaths and generally do everything possible to aid the ASSIGNEE, and its lawful successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the ASSIGNEE, and its lawful successors and assigns.

IN TESTIMONY WHEREOF, I have hereunto set my hands.

NAME OF INVENTOR (Full Legal Name) : A Reum JUN

Signature: _____



Date: _____

01/15/2019

NAME OF INVENTOR (Full Legal Name) : Hye Won RYOO

Signature: _____

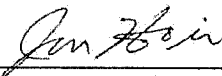


Date: _____

01/15/2019

NAME OF INVENTOR (Full Legal Name) : Ho In JUN

Signature: _____



Date: _____

01/15/2019

NAME OF INVENTOR (Full Legal Name) : Seok Keun AHN

Signature: _____



Date: _____

01/15/2019

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PATENT
REEL: 048110 FRAME: 0059

NAME OF INVENTOR (Full Legal Name) : Ji Hye YU

Signature: _____

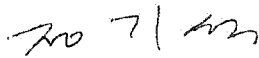


Date: _____

01 / 15 / 2019

NAME OF INVENTOR (Full Legal Name) : Gi Seok JEONG

Signature: _____



Date: _____

01 / 15 / 2019

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